

# **Comparator series**

# **Automotive Ground Sense Comparators**



# BA2903Yxxx-C, BA2901Yxx-C

## General Description

BA2903Yxxx-C/BA2901Yxx-C, integrate two or four independent high gain voltage comparator. Some features are the wide operating voltage that is 2V to 36V and low supply current. BA2903Yxxx-C, BA2901Yxx-C are manufactured for automotive requirements of engine control unit, electric power

#### Features

- AEC-Q100 Qualified
- Single or dual supply operation
- Wide operating supply voltage
- Standard comparator Pin-assignments

steering, antilock brake system, etc.

- Common-mode Input Voltage Range includes ground level, allowing direct ground sensing
- Internal ESD protection circuit
- Wide temperature range

# Application

- Engine Control Unit
- Electric Power Steering (EPS)
- Anti-Lock Braking System (ABS)
- Automotive electronics

## Key Specifications

Wide operating supply voltage

Maximum Operating Temperature

single supply: +2.0V to +36Vsplit supply:  $\pm 1.0V$  to  $\pm 18V$ 

Very low supply current

BA2903Yxxx-C 0.6mA(Typ.)
BA2901Yxx-C 0.8mA(Typ.)

Low input bias current : 50nA(Typ.)

Low input offset current : 5nA(Typ.)

Operating temperature range : -40°C to +125°C

 ●Packages
 W(Typ.) x D(Typ.) x H(Max.)

 SOP8
 5.00mm x 6.20mm x 1.71mm

 SOP14
 8.70mm x 6.20mm x 1.71mm

 SSOP-B8
 3.00mm x 6.40mm x 1.35mm

 SSOP-B14
 5.00mm x 6.40mm x 1.35mm

 MSOP8
 2.90mm x 4.00mm x 0.90mm

## Selection Guide

## Simplified schematic

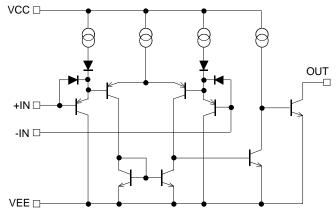
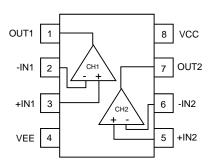


Figure 1. Simplified schematic (one channel only)

OProduct structure: Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

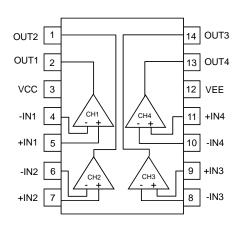
# ●Pin Configuration

BA2903YF-C : SOP8 BA2903YFV-C : SSOP-B8 BA2903YFVM-C : MSOP8



Pin No.	Pin name
1	OUT1
2	-IN1
3	+IN1
4	VEE
5	+IN2
6	-IN2
7	OUT2
8	VCC

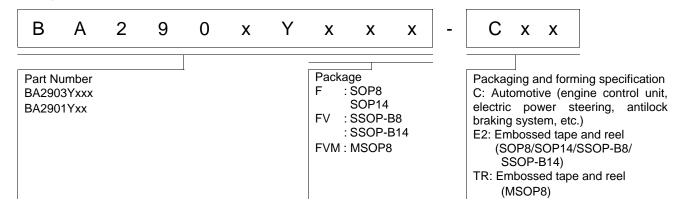
BA2901YF-C : SOP14 BA2901YFV-C : SSOP-B14



Pin No.	Pin name
1	OUT2
2	OUT1
3	VCC
4	-IN1
5	+IN1
6	-IN2
7	+IN2
8	-IN3
9	+IN3
10	-IN4
11	+IN4
12	VEE
13	OUT4
14	OUT3

		Package		
SOP8	SSOP-B8	MSOP8	SOP14	SSOP-B14
BA2903YF-C	BA2903YFV-C	BA2903YFVM-C	BA2901YF-C	BA2901YFV-C

## Ordering Information



## ●Line-up

Topr	Operating Supply Voltage	Dual/Quad	Package		Orderable Part Number
		Dual	SOP8	Reel of 2500	BA2903YF-CE2
			SSOP-B8	Reel of 2500	BA2903YFV-CE2
-40°C to +125°C	+2.0V to +36V		MSOP8	Reel of 3000	BA2903YFVM-CTR
		Quad	SOP14	Reel of 2500	BA2901YF-CE2
		Quad	SSOP-B14	Reel of 2500	BA2901YFV-CE2

● Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol		Ratings	Unit	
Supply Voltage		VCC-VEE	+36	V	
Power Dissipation		SOP8	770 <sup>*1*6</sup>		
		SSOP-B8	620 <sup>*2*6</sup>		
	Pd	MSOP8	580 <sup>*3*6</sup>	mW	
		SOP14	560 <sup>*4*6</sup>		
		SSOP-B14	870 <sup>*5*6</sup>		
Differential Input Voltage *7		Vid	+36	V	
Input Common-mode Voltage Range		Vicm	(VEE-0.3) to (VEE+36)	V	
Input Current **		li	-10	mA	
Operating Supply Voltage		Vopr	+2.0 to +36 (±1.0 to ±18)	V	
Operating Temperature Range		Topr	-40 to +125	°C	
Storage Temperature Range		Tstg	-55 to +150	°C	
Maximum junction Temperature		Tjmax	+150	°C	

Note: Absolute maximum rating item indicates the condition which must not be exceeded.

Application if voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

<sup>\*1</sup> To use at temperature above Ta=25°C reduce 6.2 mW/°C.

<sup>\*2</sup> To use at temperature above Ta=25°C reduce 5.5mW/°C.

<sup>\*3</sup> To use at temperature above Ta=25°C reduce 4.7mW/°C.

<sup>\*4</sup> To use at temperature above Ta=25°C reduce 4.9mW/°C.

<sup>\*5</sup> To use at temperature above Ta=25°C reduce 7.0mW/°C.

<sup>\*6</sup> Mounted on a FR4 glass epoxy PCB(70mm×70mm×1.6mm).

<sup>\*7</sup> The voltage difference between inverting input and non-inverting input is the differential input voltage. Then input pin voltage is set to more than VEE.

<sup>\*8</sup> An excessive input current will flow when input voltages of lesser than VEE-0.6V are applied. The input current can be set to less than the rated current by adding a limiting resistor.

## Electrical Characteristics

OBA2903Yxxx-C (Unless otherwise specified VCC=+5V, VEE=0V)

Daramatar	Symbol Temperature Limits		Unit	Conditions				
Parameter	Symbol	range	Min.	Тур.	Max.	Unit	Conditions	
Input Offset Voltage *9	Vio	25°C	-	2	4	mV	OUT=1.4V	
Input Offset Voltage	VIO	Full range	-	-	5	IIIV	VCC=5 to 36V, OUT=1.4V	
Input Offset Current *9	lio	25°C		5	40	<b>~</b> Λ	OUT=1.4V	
Input Onset Current	110	Full range	-	-	50	nA	O01=1.4V	
Input Bias Current *9	lb	25°C	-	50	250	nA	OUT=1.4V	
Input Bias Current	ID	Full range	-	-	275	IIA	O01=1.4V	
Input Common-mode	Vicm	25°C	0	-	VCC-1.5	V		
Voltage Range	VICITI	Full range	0	-	VCC-2.0	V	-	
Large Signal Voltage Gain	Av	25°C	88	100	-	dB	VCC=15V, OUT=1.4 to 11.4V	
Large Signal Voltage Gain	Av	Full range	74	-	-	uБ	RL=15k $\Omega$ , VRL=15V	
Supply Current	ICC	25°C	-	0.6	1	mA	OUT=open	
	100	Full range	-	-	2.5	шл	OUT=open, VCC=36V	
Output Sink Current *10	Isink	25°C	6	16	-	mΑ	+IN=0V, -IN=1V, VOL=1.5V	
Output Saturation Voltage	VOL	25°C	-	150	400	mV	+IN=0V, -IN=1V,	
(Low level output voltage)	VOL	Full range	-	-	700	1117	Isink=4mA	
Output Leakage Current	lleak	25°C	-	0.1	-	μA	+IN=1V, -IN=0V, VOH=5V	
(High level output current)	lican	Full range	-	-	1	μΛ	+IN=1V, -IN=0V, VOH=36V	
			_	1.3	_		RL= $5.1k\Omega$ , VRL= $5V$	
Response Time	Tre	25°C -		1.5	_	110	IN=100mV <sub>P-P</sub> , overdrive=5mV	
	116	25 0	_	0.4	_	μs	RL=5.1k $\Omega$ , VRL=5V, IN=TTL	
			_	0.4	_		Logic Swing, VREF=1.4V	
Operable Frequency	Fopr	25℃	100	_	_	kHz	VCC=5V, RL= $2k\Omega$ , +IN= $1.5V$ , -IN= $5Vp$ - $p$	
Operable Frequency	i opi	25 0 100		_	_	IXI IZ	(Duty 50% Rectangular Pulse)	

<sup>\*9</sup> Absolute value

# OBA2901Yxx-C (Unless otherwise specified VCC=+5V, VEE=0V)

Parameter	Symbol	Temperature		Limits		Unit	Conditions	
Parameter	Symbol	range	Min.	Тур.	Max.	Offic	Conditions	
Input Offset Voltage *11	Vio	25°C	-	2	4	mV	OUT=1.4V	
input Offset Voltage	VIO	Full range	-	-	5	IIIV	VCC=5 to 36V, OUT=1.4V	
Input Offset Current *11	lio	25°C	-	5	40	nA	OUT=1.4V	
input Onset Current	110	Full range	-	-	50	IIA	001=1.40	
Input Bias Current *11	lb	25°C	-	50	250	nA	OUT=1.4V	
Input bias Current	ID	Full range	-	-	275	ПА	001=1.40	
Input Common-mode	Vicm	25°C	0	-	VCC-1.5	V		
Voltage Range	VICITI	Full range	0	-	VCC-2.0	V	-	
Large Signal Voltage Gain	Av	25°C	88	100	-	dB	VCC=15V, OUT=1.4 to 11.4V	
Large Signal Voltage Gain	Av	Full range	74	-	-	uБ	RL=15kΩ, VRL=15V	
Supply Current	ICC	25°C	-	0.8	2	mA	OUT=open	
Supply Current	icc	Full range	-	-	2.5	ША	OUT=open, VCC=36V	
Output Sink Current *12	Isink	25°C	6	16	-	mΑ	+IN=0V, -IN=1V, VOL=1.5V	
Output Saturation Voltage	VOL	25°C	-	150	400	mV	+IN=0V, -IN=1V,	
(Low level output voltage)	VOL	Full range	-	-	700	IIIV	Isink=4mA	
Output Leakage Current	lleak	25°C	-	0.1	-	μA	+IN=1V, -IN=0V, VOH=5V	
(High level output current)	lleak	Full range	-	-	1	μΑ	+IN=1V, -IN=0V, VOH=36V	
			_	1.3	_		RL=5.1kΩ, VRL=5V	
Response Time	Tre	25°C	-	1.3	-		IN=100mV <sub>P-P</sub> , overdrive=5mV	
	116	25 C	_	0.4	_	μs	RL=5.1kΩ, VRL=5V, IN=TTL	
			-	0.4	-		Logic Swing, VREF=1.4V	
Operable Frequency	Fopr	25°C	100 -			kHz	VCC=5V, RL=2kΩ, +IN=1.5V, -IN=5Vp-p	
Operable Frequency	горі	23 0 100		-	KIZ	(Duty 50% Rectangular Pulse)		

<sup>\*11</sup> Absolute value

<sup>\*10</sup> Under high temperatures, please consider the power dissipation when selecting the output current.

When the output terminal is continuously shorted the output current reduces the internal temperature by flushing.

<sup>\*12</sup> Under high temperatures, please consider the power dissipation when selecting the output current.

When the output terminal is continuously shorted the output current reduces the internal temperature by flushing.

## **Description of Electrical Characteristics**

Described below are descriptions of the relevant electrical terms used in this datasheet. Items and symbols used are also shown. Note that item name and symbol and their meaning may differ from those on another manufacturer's document or general document.

## 1. Absolute maximum ratings

Absolute maximum rating items indicate the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

## 1.1 Supply Voltage (VCC-VEE)

Indicates the maximum voltage that can be applied between the positive power supply terminal and negative power supply terminal without deterioration or destruction of characteristics of internal circuit.

## 1.2 Differential Input Voltage (Vid)

Indicates the maximum voltage that can be applied between non-inverting and inverting terminals without damaging the IC.

# 1.3 Input Common-mode Voltage Range (Vicm)

Indicates the maximum voltage that can be applied to the non-inverting and inverting terminals without deterioration or destruction of electrical characteristics. Input common-mode voltage range of the maximum ratings does not assure normal operation of IC. For normal operation, use the IC within the input common-mode voltage range characteristics.

## 1.4 Operating and Storage Temperature Ranges (Topr, Tstg)

The operating temperature range indicates the temperature range within which the IC can operate. The higher the ambient temperature, the lower the power consumption of the IC. The storage temperature range denotes the range of temperatures the IC can be stored under without causing excessive deterioration of the electrical characteristics.

## 1.5 Power Dissipation (Pd)

Indicates the power that can be consumed by the IC when mounted on a specific board at the ambient temperature 25°C (normal temperature). As for package product, Pd is determined by the temperature that can be permitted by the IC in the package (maximum junction temperature) and the thermal resistance of the package.

## 2. Electrical characteristics

## 2.1 Input Offset Voltage (Vio)

Indicates the voltage difference between non-inverting terminal and inverting terminals. It can be translated into the input voltage difference required for setting the output voltage at 0 V.

## 2.2 Input Offset Current (Iio)

Indicates the difference of input bias current between the non-inverting and inverting terminals.

## 2.3 Input Bias Current (lb)

Indicates the current that flows into or out of the input terminal. It is defined by the average of input bias currents at the non-inverting and inverting terminals.

## 2.4 Input Common-mode Voltage Range (Vicm)

Indicates the input voltage range where IC normally operates.

# 2.5 Large Signal Voltage Gain (Av)

Indicates the amplifying rate (gain) of output voltage against the voltage difference between non-inverting terminal and inverting terminal. It is normally the amplifying rate (gain) with reference to DC voltage.

Av = (Output voltage) / (Differential input voltage)

## 2.6 Supply current (ICC)

Indicates the current that flows within the IC under specified no-load conditions.

## 2.7 Output Sink Current (Isink)

Indicates the current flowing into the IC under specific output conditions.

# 2.8 Output Saturation Voltage (Low level output voltage) (VOL)

Indicates the lower limit of output voltage under specific input and output conditions.

## 2.9 Output Leakage Current( High level output current) (Ileak)

Indicates the current that flows into the IC under specific input and output conditions.

## 2.11 Response Time (Tre)

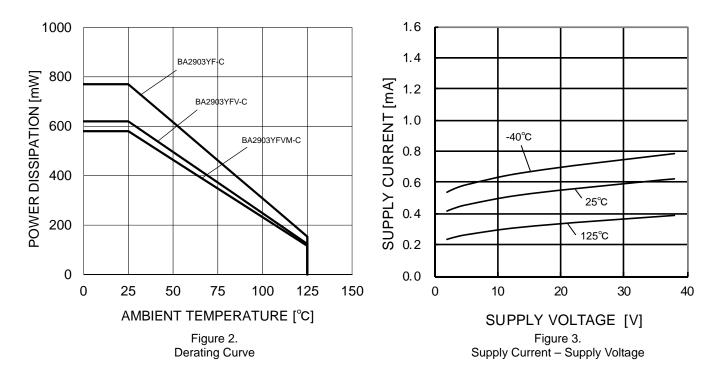
Indicates the time interval between the application of input and output conditions.

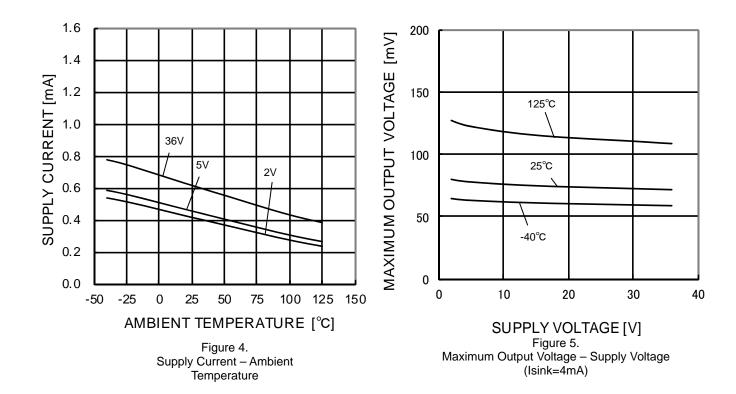
# 2.10 Operable Frequency (Fopr)

Indicates minimum frequency that IC moves under specific conditions..

## **●**Typical Performance Curves

OBA2903Yxxx-C





OBA2903Yxxx-C

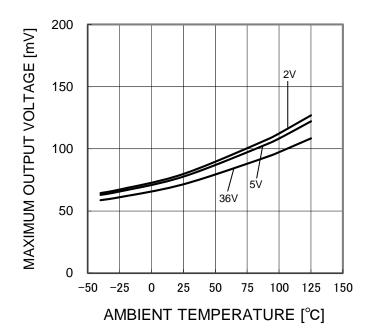


Figure 6.

Maximum Output Voltage – Ambient Temperature
(Isink=4mA)

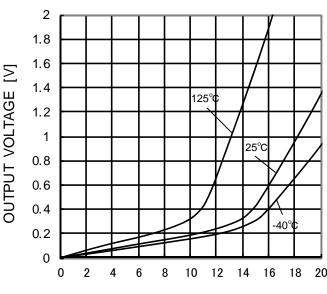


Figure 7.
Output Voltage – Output Sink Current
(VCC=5V)

**OUTPUT SINK CURRENT [mA]** 

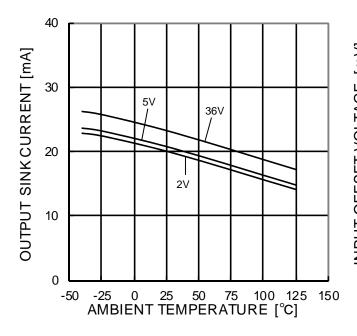


Figure 8.

Output Sink Current – Ambient Temperature (OUT=1.5V)

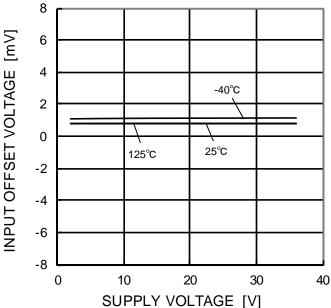


Figure 9.
Input Offset Voltage – Supply Voltage

OBA2903Yxxx-C

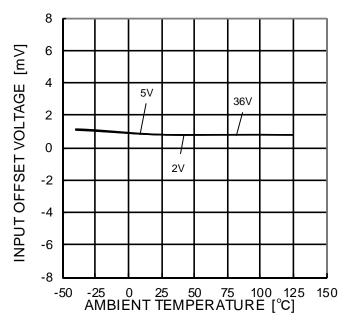
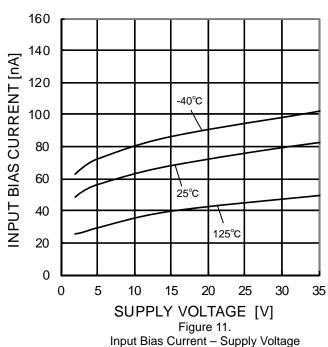


Figure 10.
Input Offset Voltage – Ambient
Temperature



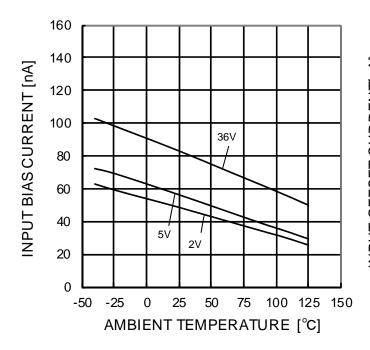


Figure 12.
Input Bias Current – Ambient Temperature

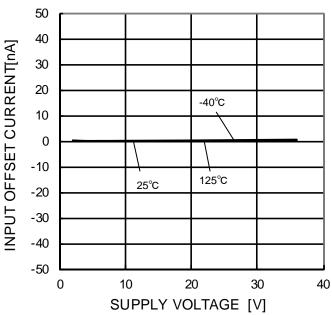
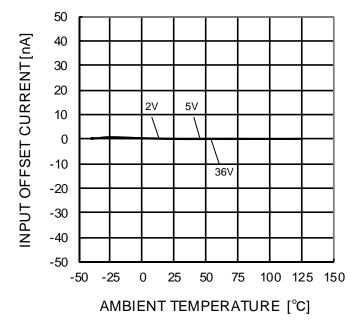


Figure 13.
Input Offset Current – Supply Voltage

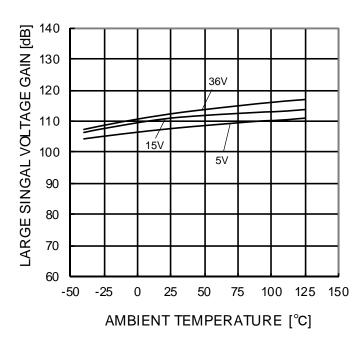
OBA2903Yxxx-C



140 LARGE SINGAL VOLTAGE GAIN [dB] 130 125°C 120 110 100 -40°C 90 80 70 60 0 10 20 30 40 SUPPLY VOLTAGE [V]

Figure 14.
Input Offset Current
– Ambient Temperature

Figure 15.
Large Signal Voltage Gain
– Supply Voltage



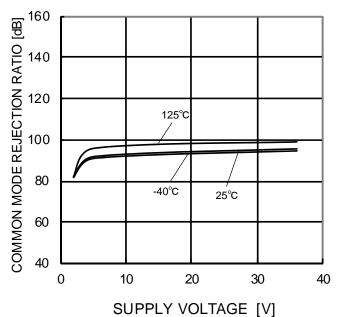
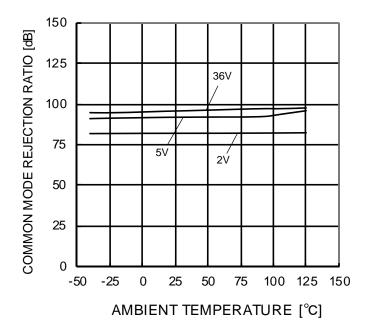


Figure 16.
Large Signal Voltage Gain
– Ambient Temperature

Figure 17.
Common Mode Rejection Ratio
– Supply Voltage

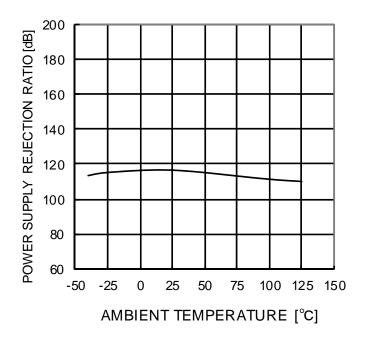
OBA2903Yxxx-C



6 INPUT OFFSET VOLTAGE [mV] -40°C 25°C 125°C 2 0 -2 -4 -6 -1 0 1 2 3 4 5 INPUT VOLTAGE [V]

Figure 18.
Common Mode Rejection Ratio
– Ambient Temperature

Figure 19.
Input Offset Voltage – Input Voltage (VCC=5V)



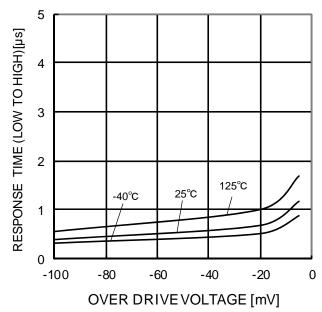


Figure 20.
Power Supply Rejection Ratio
– Ambient Temperature

Figure 21. Response Time (Low to High) – Over Drive Voltage (VCC=5V, VRL=5V, RL=5.1k $\Omega$ )

OBA2903Yxxx-C

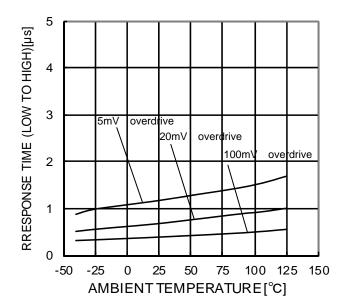


Figure 22.
Response Time (Low to High)
– Ambient Temperature
(VCC=5V, VRL=5V, RL=5.1kΩ)

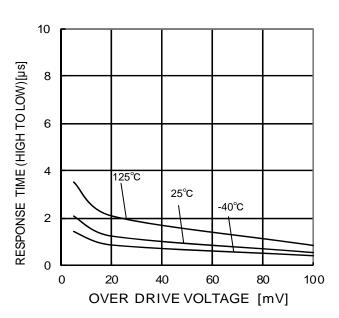


Figure 23.
Response Time (High to Low)

– Over Drive Voltage
(VCC=5V, VRL=5V, RL=5.1kΩ)

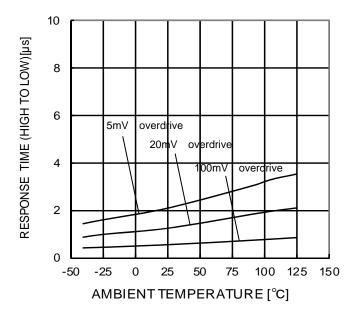
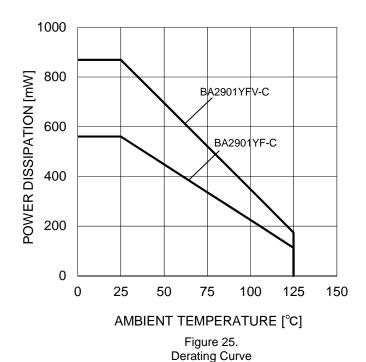


Figure 24.
Response Time (High to Low)
– Ambient Temperature
(VCC=5V, VRL=5V, RL=5.1kΩ)

## **●**Typical Performance Curves

OBA2901Yxx-C



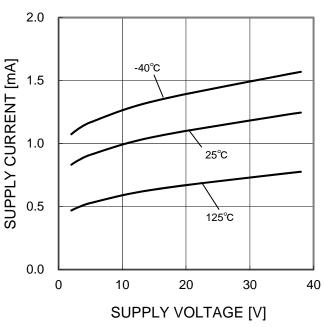
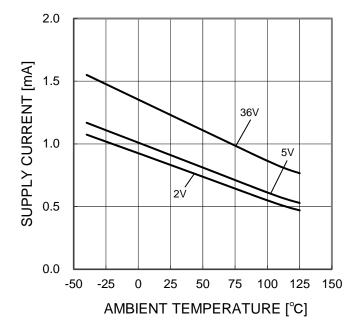
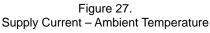


Figure 26. Supply Current – Supply Voltage





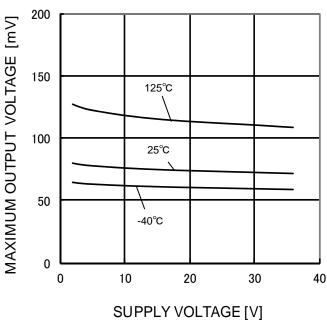


Figure 28.

Maximum Output Voltage – Supply Voltage (Isink=4mA)

OBA2901Yxx-C

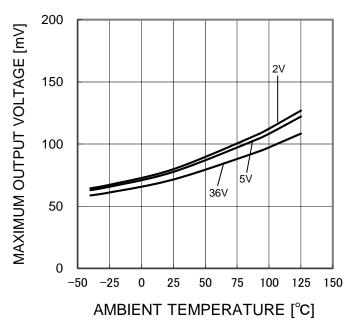


Figure 29.

Maximum Output Voltage – Ambient Temperature (Isink=4mA)

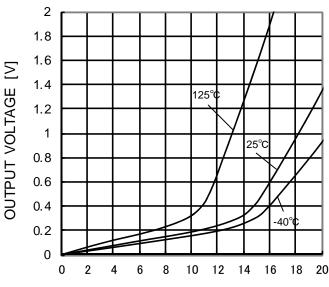


Figure 30.
Output Voltage – Output Sink Current (VCC=5V)

**OUTPUT SINK CURRENT [mA]** 

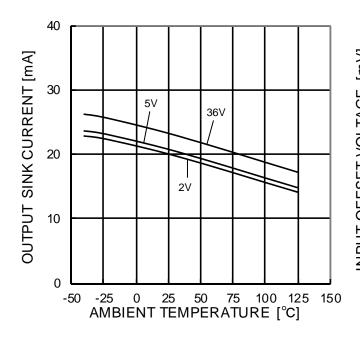


Figure 31.
Output Sink Current – Ambient Temperature (OUT=1.5V)

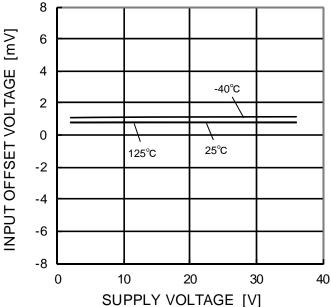


Figure 32.
Input Offset Voltage – Supply Voltage

OBA2901Yxx-C

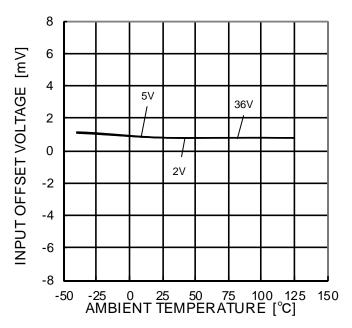


Figure 33.
Input Offset Voltage – Ambient
Temperature

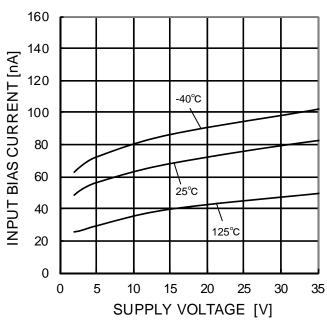


Figure 34.
Input Bias Current – Supply Voltage

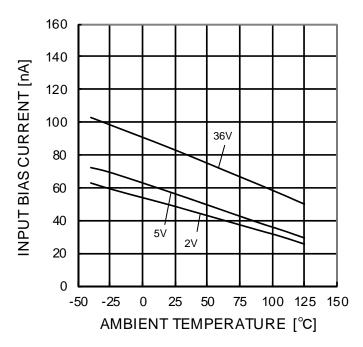


Figure 35.
Input Bias Current – Ambient Temperature

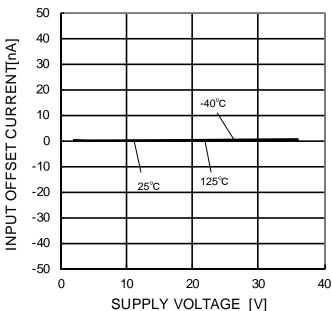
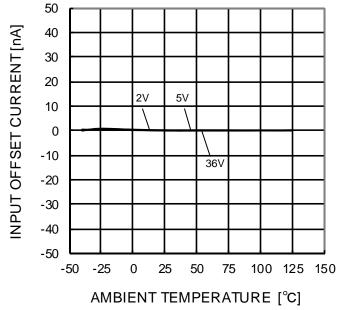


Figure 36.
Input Offset Current – Supply Voltage

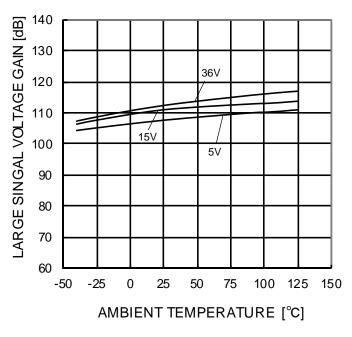
OBA2901Yxx-C



140 -ARGE SINGAL VOLTAGE GAIN [dB] 130 125°C 120 110 100 -40°C 90 80 70 60 0 10 20 30 40 SUPPLY VOLTAGE [V]

Figure 37.
Input Offset Current
– Ambient Temperature

Figure 38. Large Signal Voltage Gain – Supply Voltage



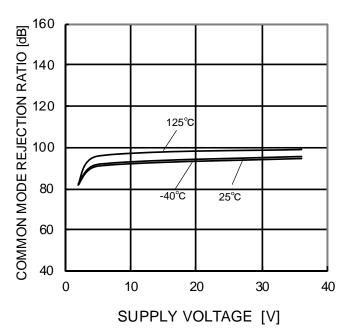
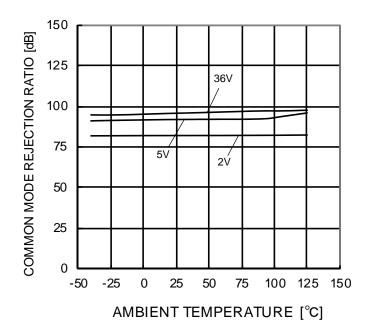


Figure 39.
Large Signal Voltage Gain
– Ambient Temperature

Figure 40.
Common Mode Rejection Ratio
– Supply Voltage

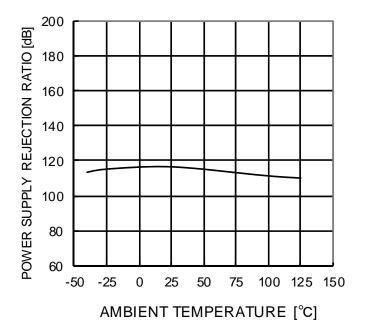
OBA2901Yxx-C



6 INPUT OFFSET VOLTAGE [mV] 40°C 25°C 125°C 2 0 -2 -4 -6 0 2 3 5 -1 1 4 INPUT VOLTAGE [V]

Figure 41.
Common Mode Rejection Ratio
– Ambient Temperature

Figure 42.
Input Offset Voltage – Input Voltage (VCC=5V)



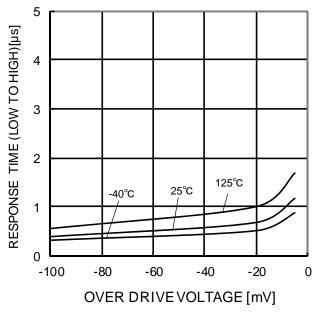


Figure 43.
Power Supply Rejection Ratio
– Ambient Temperature

Figure 44.
Response Time (Low to High) – Over Drive Voltage (VCC=5V, VRL=5V, RL=5.1kΩ)

OBA2901Yxx-C

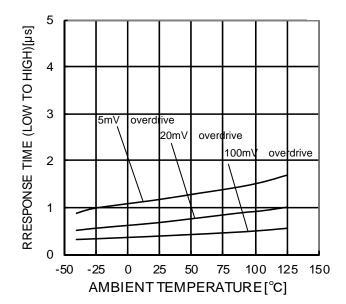


Figure 45.
Response Time (Low to High)
– Ambient Temperature
(VCC=5V, VRL=5V, RL=5.1kΩ)

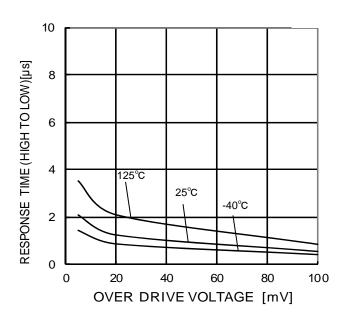


Figure 46.
Response Time (High to Low)
– Over Drive Voltage
(VCC=5V, VRL=5V, RL=5.1kΩ)

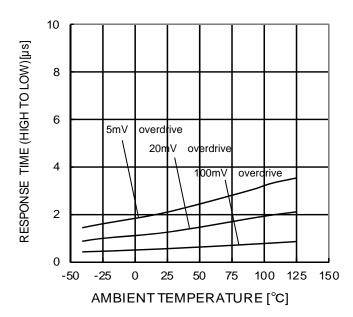


Figure 47.
Response Time (High to Low)
– Ambient Temperature
(VCC=5V, VRL=5V, RL=5.1kΩ)

## ●Power Dissipation

Power dissipation (total loss) indicates the power that the IC can consume at Ta=25°C (normal temperature). As the IC consumes power, it heats up, causing its temperature to be higher than the ambient temperature. The allowable temperature that the IC can accept is limited. This depends on the circuit configuration, manufacturing process, and consumable power.

Power dissipation is determined by the allowable temperature within the IC (maximum junction temperature) and the thermal resistance of the package used (heat dissipation capability). Maximum junction temperature is typically equal to the maximum storage temperature. The heat generated through the consumption of power by the IC radiates from the mold resin or lead frame of the package. Thermal resistance, represented by the symbol  $\theta$ ja°C/W, indicates this heat dissipation capability. Similarly, the temperature of an IC inside its package can be estimated by thermal resistance.

Figure 50. (a) shows the model of the thermal resistance of the package. The equation below shows how to compute for the Thermal resistance ( $\theta$ )a, given the ambient temperature (Ta), junction temperature (Tj), and power dissipation (Pd).

$$\theta$$
ja = (Tjmax-Ta) / Pd °C/W · · · · · (I)

The Derating curve in Figure 48. (b) indicates the power that the IC can consume with reference to ambient temperature. Power consumption of the IC begins to attenuate at certain temperatures. This gradient is determined by Thermal resistance  $(\theta | a)$ , which depends on the chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc. This may also vary even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Figure 49. (c),(d) shows an example of the derating curve for BA2903Yxxx-C, BA2901Yxx-C.

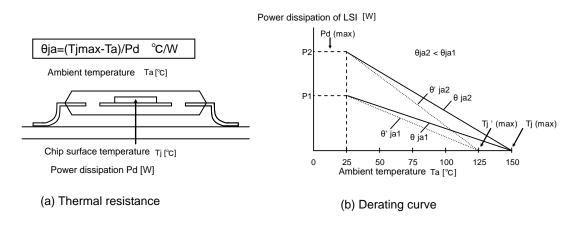
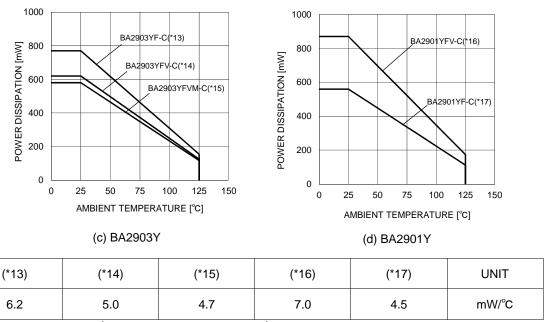


Figure 48. Thermal resistance and derating



When using the unit above Ta=25°C, subtract the value above per degree°C.

Permissible dissipation is the value when FR4 glass epoxy board 70mm×70mm×1.6mm(cooper foil area below 3%) is mounted.

Figure 49. Derating curve

## Application Information

## **NULL** method condition for Test circuit 1

VCC,VEE,EK,Vicm Unit: V

Parameter	VF	S1	S2	<b>S</b> 3	Vcc	VEE	EK	Vicm	Calculation
Input Offset Voltage	VF1	ON	ON	ON	5~36	0	-1.4	0	1
Input Offset Current	VF2	OFF	OFF	ON	5	0	-1.4	0	2
Input Pigo Current	VF3	OFF	ON	ON		0	-1.4	0	3
Input Bias Current	VF4	ON	OFF	OFF ON 5	5	0	-1.4	0	3
Lorgo Signal Voltago Cain	VF5	ON	ON ON		15	0	-1.4	0	4
Large Signal Voltage Gain	VF6	ON	ON	ON	15	0	-11.4	0	4

- Calculation -
- 1. Input Offset Voltage (Vio)

$$Vio = \frac{\left| VF1 \right|}{1 + RF/RS} \quad [V]$$

2. Input Offset Current (lio)

$$lio = \frac{\left| VF2 - VF1 \right|}{Ri \times (1 + RF / RS)} \quad [A]$$

3. Input Bias Current (lb)

$$lb = \frac{\left| VF4 - VF3 \right|}{2 \times Ri \times (1 + RF/RS)} \quad [A]$$

4. Large Signal Voltage Gain (Av)

$$Av = 20 \times Log \frac{\Delta EK \times (1 + RF/RS)}{\mid VF5 - VF6 \mid} \quad \text{[dB]}$$

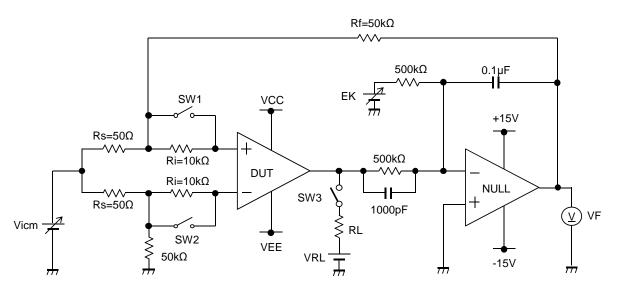


Figure 50. Test circuit 1 (one channel only)

## **Switch Condition for Test Circuit 2**

iten Condition for Test Official 2								
SW No.		SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7
Supply Current		OFF						
Output Sink Current	VOL=1.5V	OFF	ON	ON	OFF	OFF	OFF	ON
Output Saturation Voltage	Isink=4mA	OFF	ON	ON	OFF	ON	ON	OFF
Output Leakage Current	VOH=36V	OFF	ON	ON	OFF	OFF	OFF	ON
Response Time	RL=5.1kΩ, VRL=5V	ON	OFF	ON	ON	OFF	OFF	OFF

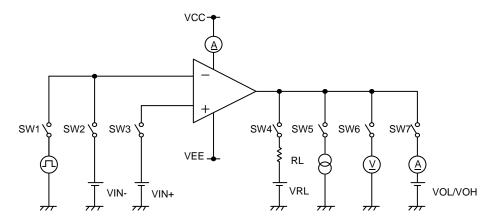


Figure 51. Test Circuit 2 (one channel only)

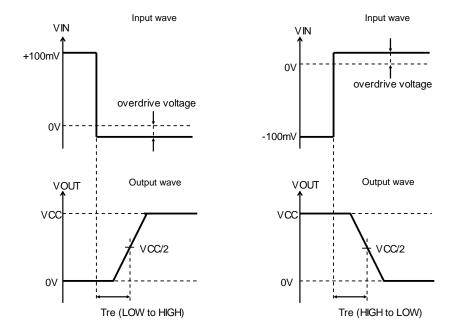
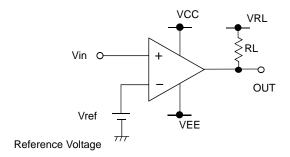


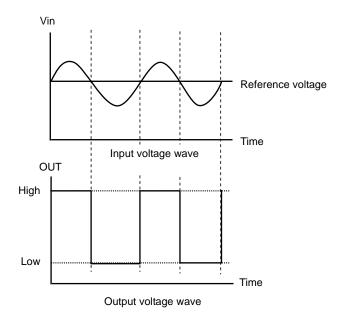
Figure 52. Response Time

## Application example

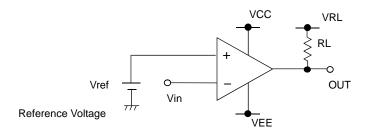
## OReference voltage is -IN



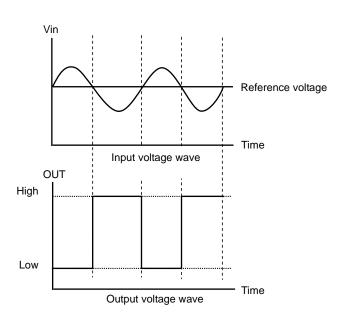
While the input voltage(Vin) is higher that the reference voltage, the output voltage remains high. In case the input voltage becomes lower than the reference voltage, the output voltage will turn low.



# OReference voltage is +IN



While the input voltage(Vin) is smaller that the reference voltage, the output voltage remains high. In case the input voltage becomes higher than the reference voltage, the output voltage will turn low.



## Operational Notes

#### 1) Unused circuits

When there are unused comparators, it is recommended that they are connected as in Figure 53. ,setting the non-inverting input terminal to a potential within the in-phase input voltage range (Vicm).

Vicm VEE

Please keep this potential in Vicm VCC-1.5V>Vicm>VEE

## 2) Input voltage

Applying VEE +36V to the input terminal is possible without causing deterioration of the electrical characteristics or destruction, regardless of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common mode input voltage range of the electric characteristics.

Figure 53. Example of application circuit for unused comparator

## 3) Power supply (single / dual)

The comparator operates when the voltage supplied is between VCC and VEE. Therefore, the signal supply comparator can be used as a dual supply comparator as well.

## 4) Power dissipation Pd

Using the unit in excess of the rated power dissipation may cause deterioration in electrical characteristics including reduced current capability due to the rise of chip temperature. Therefore, please take into consideration the power dissipation (Pd) under actual operating conditions and apply a sufficient margin in thermal design. Refer to the thermal derating curves for more information.

# 5) Short-circuit between pins and erroneous mounting

Be careful when mounting the IC on printed circuit boards. The IC may be damaged if it is mounted in a wrong orientation or if pins are shorted together. Short circuit may be caused by conductive particles caught between the pins.

## 6) Terminal short-circuits

When the output and VCC terminals are shorted, excessive output current may flow, resulting in undue heat generation and, subsequently, destruction.

# 7) Operation in a strong electromagnetic field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

## 8) Radioactive rays

This IC is not designed protection against radioactive rays.

## 9) IC handling

Applying mechanical stress to the IC by deflecting or bending the board may cause fluctuations in the electrical characteristics due to piezo resistance effects.

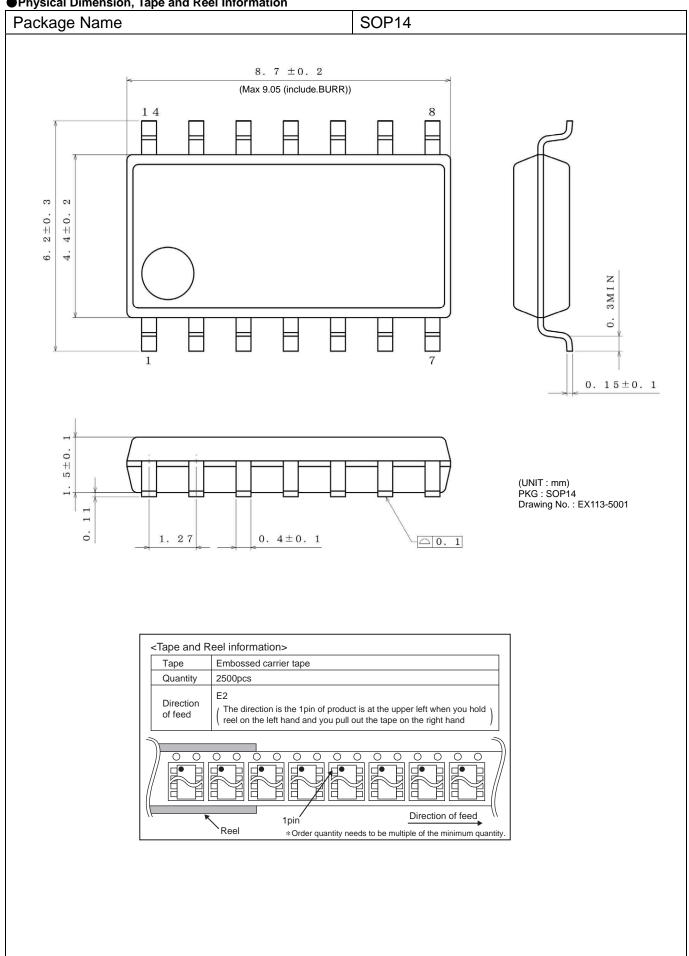
## 10) Board inspection

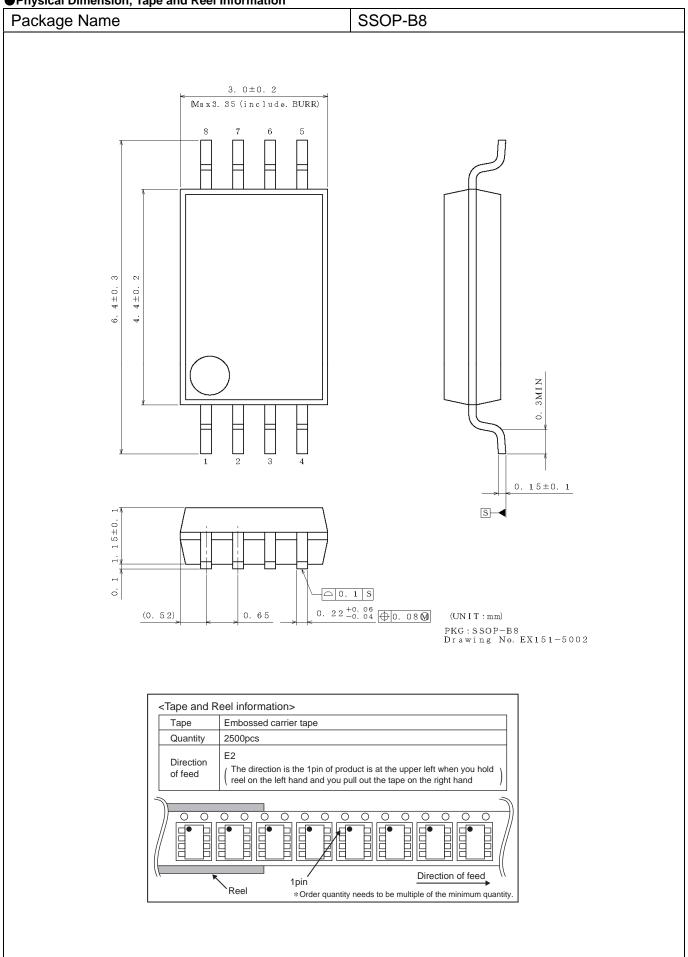
Connecting a capacitor to a pin with low impedance may stress the IC. Therefore, discharging the capacitor after every process is recommended. In addition, when attaching and detaching the jig during the inspection phase, ensure that the power is turned OFF before inspection and removal. Furthermore, please take measures against ESD in the assembly process as well as during transportation and storage.

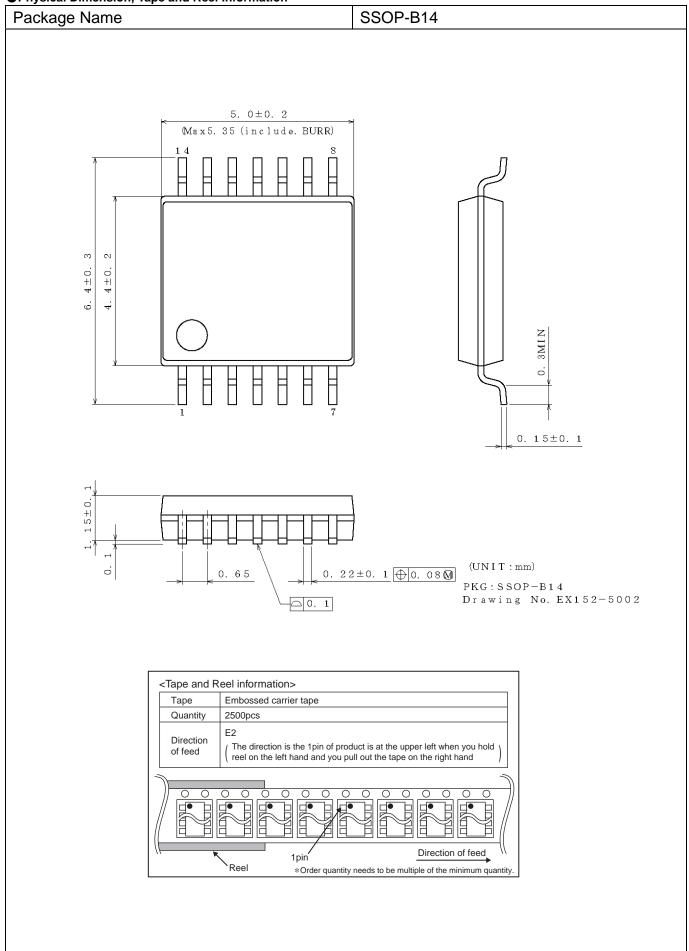
Datasheet BA2903Yxxx-C, BA2901Yxx-C ●Physical Dimension, Tape and Reel Information Package Name SOP8 5.  $0 \pm 0$ . 2 (Max 5.35 (include.BURR)) 5  $\mathfrak{S}$ N  $2 \pm 0$ . +0 4  $9\pm0$ . 3MIN 0 0 0.  $17^{+0.1}_{-0.05}$ 0.595 S +0 2 (UNIT : mm) PKG : SOP8 Drawing No. : EX112-5001-1 0 0. 42±0. 1 O. 1 S 1. 27 <Tape and Reel information> Embossed carrier tape Tape Quantity 2500pcs Direction The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand of feed

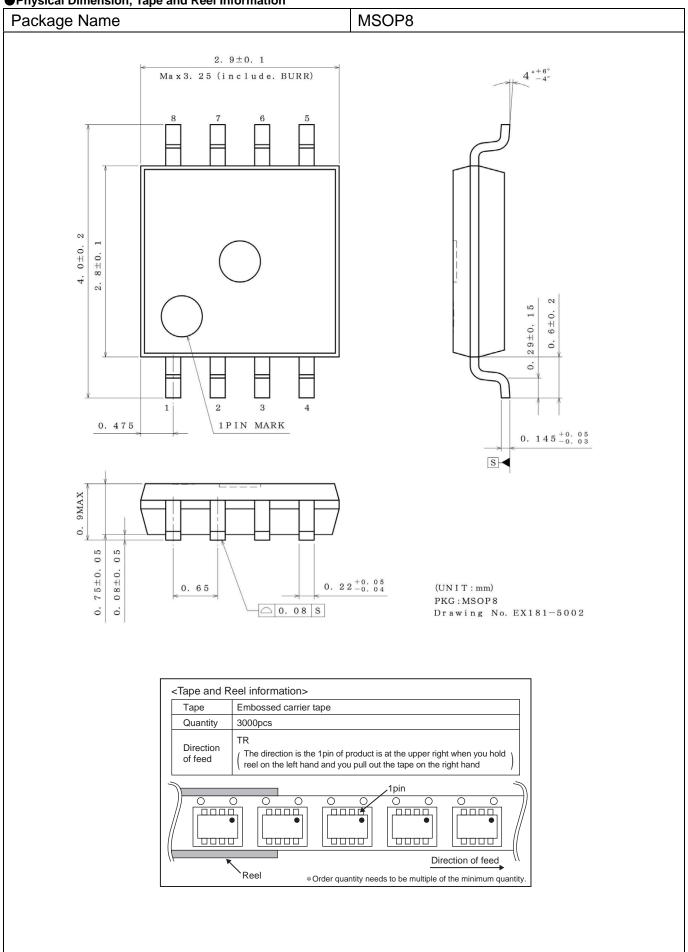
Direction of feed

\*Order quantity needs to be multiple of the minimum quantity.

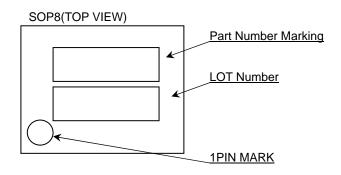


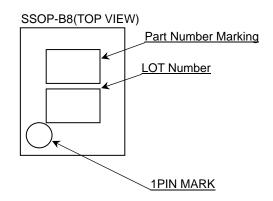


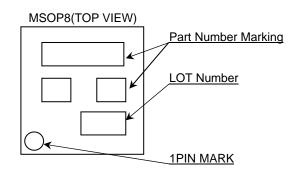


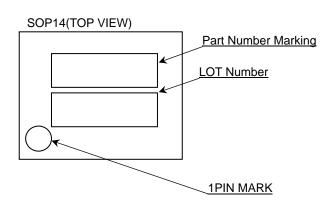


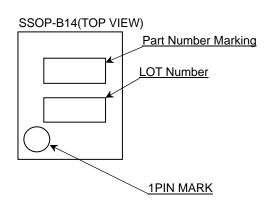
# Marking Diagrams





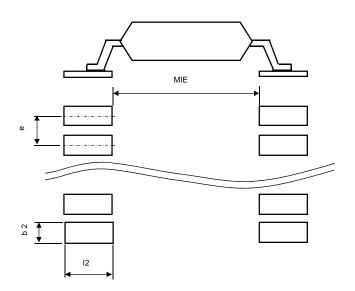






Product N	Name	Package Type	Marking
	F-C	SOP8	2903Y
BA2903Y	FV-C	SSOP-B8	03Y
	FVM-C	MSOP8	2903Y
BA2901Y	F-C	SOP14	BA2901YF
DAZ9011	FV-C	SSOP-B14	2901Y

# ●Land pattern data



SOP8, SSOP-B8, MSOP8 SOP14, SSOP-B14

All dimensions in mm

Package	Land pitch e	Land space MIE	Land length ≧ℓ 2	Land width b2
SOP8 SOP14	1.27	4.60	1.10	0.76
SSOP-B8 SSOP-B14	0.65	4.60	1.20	0.35
MSOP8	0.65	2.62	0.99	0.35

# Revision History

Date	Revision	Changes
11.APR.2012	001	New Release
21.JAN.2013	002	Land pattern data inserted.
11.MAR.2013	003	Input offset voltage, Input offset current limit (Temp=25°C) changed.  Description of Physical Dimension, Tape and Reel Information changed.
8.MAY.2013	004	SOP8, SSOP-B8, MSOP8 Power dissipation corrected. SSOP-B8, SSOP-B14 corrected.

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If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV		CLASSⅢ	

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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl2, H<sub>2</sub>S. NH<sub>3</sub>. SO<sub>2</sub>. and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [q] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

# **Precautions Regarding Application Examples and External Circuits**

- If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

# **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Rev.002

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